Overview

HP ProBook 450 G6 Notebook PC



Left

- 1. Internal Microphones (2)
- 2. Webcam
- 3. Webcam LED
- 4. Clickpad
- 5. Hard Drive LED

- 6. SD Card Reader
- 7. Thermal Vent
- 8. USB 2.0 Port
- 9. Standard Security Lock Slot (Lock sold separately)
- 10. Power Button



Overview



Right

- 1. Power Connector
- 2. USB Type-C[™] 3.1 Gen 1 Port
- 3. Ethernet Port (RJ-45)
- 4. HDMI Port (Cable not included)

- 5. USB 3.1 Gen 1 Port
- 6. USB 3.1 Gen 1 Port
- 7. Headphone/Microphone Combo Jack
- 8. HP Fingerprint Sensor



Overview

At a Glance

- Preinstall with Windows 10 versions or FreeDOS 3.0
- Choice of 8th Generation Intel® Core™ i7, i5, i3 processors
- Display include your choice of 39.62 cm (15.6") diagonal HD, Ultra Wide Viewing Angle FHD, Touch or Non-Touch
- Optional Nvidia GeForce MX250 and MX130 with 2 GB GDDR5 dedicated video memory or integrated Intel® HD Graphics 610 or Intel® UHD 620
- Enhanced security features including TPM2.0, HP BIOSphere, Hardware enforced Firmware Protection, HP Fingerprint Sensor and IR camera
- Passed 19 items of MIL-STD 810G testing plus an additional 120,000 hours of reliability testing through HP's Total Test Process¹
- Weight starting at 4.41 lbs (2.0 kgs)
- HP Long-Life Rechargeable battery, with HP Fast Charge Technology recharges 50% in 30 minutes²
- Supports wireless LAN and wireless WWAN options for connectivity on the go
- Up to 512 GB Solid State Drives and 1 TB Hard Drive
- Up to 32 GB total system memory
- 720p HD webcam, IR camera for face authentication with Windows Hello
- Spill-resistant and optional backlit Keyboard with numeric keypad, and Clickpad with multi-touch gestures enabled, taps enabled as default.
- Enjoy the rich conferencing experience of the Skype for Business™ Certified HP ProBook 450
- MIL STD 810G testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Damage under the MIL STD test conditions or any accidental damage requires an optional HP Accidental Damage Protection Care Pack.
- 2. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode when used with the power adapter provided with the notebook. After charging has reached 50% capacity, charging speed will return to normal. Charging time may vary +/-10% due to System tolerance.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Technical Specifications

PRODUCT NAMES

HP ProBook 450 G6 Notebook PC

OPERATING SYSTEMS

Preinstalled Windows 10 Pro 64¹

Windows 10 Pro 64 (National Academic only)²

Windows 10 Home 641

Windows 10 Home Single Language 64¹ Windows 10 China Government Edition

FreeDOS 3.0

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

PROCESSORS

Intel® Core™ i7-8565U processor with Intel® UHD Graphics 620 (1.8 GHz base frequency, up to 4.6 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6}

Intel® Core™ i5-8265U with Intel® UHD Graphics 620 Graphics (1.6 GHz base frequency, up to 3.9 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores) 3,4,5,6

Intel® Core™ i5-8365U vPro™ processor with Intel® UHD Graphics 620 (1.6 GHz base frequency, up to 4.1 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores)^{3,4,5,6}

Intel® Core™ i3-8145U with Intel® UHD Graphics 620 Graphics (2.1 GHz base frequency, up to 3.9 GHz with Intel® Turbo Boost Technology, 4 MB L3 cache, 2 cores) 3,4,5,6

Intel® Core™ i7+ 8565U processor (Core™ i7 and 16 GB Intel® Optane™ memory) with Intel® UHD Graphics 620 (1.8 GHz base frequency, up to 4.6 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6,7}

Intel® Core™ i5+ 8265U processor (Core™ i5 and 16 GB Intel® Optane™ memory) with Intel® UHD Graphics 620 (1.6 GHz base frequency, up to 3.9 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores) 3,4,5,6,7

Intel® Celeron® 4205U processor with Intel® HD Graphics 610 (1.8 GHz base frequency, 2 MB L3 cache, 2 cores)^{3,4,5,6} Intel® Pentium® 5405U processor with Intel® HD Graphics 610 (2.3 GHz base frequency, 2 MB L3 cache, 2 cores)^{3,4,5,6}

Processors Family

8th Generation Intel® Core™ i7 processor (i7-8565U)⁶ 8th Generation Intel® Core™ i5 processor (i5-8265U, 8365U)⁶ 8th Generation Intel® Core™ i3 processor (i3-8145U)⁶ Intel® Pentium® processor (5405U)⁶ Intel® Celeron® processor (4205U)⁶

3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.



Technical Specifications

- 4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
- 5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.
- 6. NOTE: In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.
- 7. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system and requires configuration with an optional Intel® Core™ i(5 or 7)+ processor.

CHIPSET

Integrated with processor

GRAPHICS

Integrated

Intel® UHD graphics 6208

Discrete

NVIDIA® GeForce® MX130 (2 GB DDR5 dedicated)9 NVIDIA® GeForce® MX250 (2 GB DDR5 dedicated)9

Supports

Support HD decode, DX12, HDMI 1.4b up to 4K 30Hz Support CUDA, Optimus, PhysX, GPU Boost 2.0

- 8. HD content required to view HD images.
- 9. Integrated graphics depends on processor. NVIDIA® Optimus™ technology requires an Intel processor, plus an NVIDIA® GeForce® discrete graphics configuration and is available on Windows 10 Pro OS. With NVIDIA® Optimus™ technology, full enablement of all discrete graphics video and display features may not be supported on all systems (e.g. OpenGL applications will run on the integrated GPU or the APU as the case may be).

DISPLAYS

Internal

Non-Touch

39.6 cm (15.6") diagonal HD SVA eDP anti-glare LED-backlit slim, 220 cd/m 2 , 67% sRGB for two WLAN antennas (1366 x 768) 8,10

39.6 cm (15.6") diagonal HD SVA eDP anti-glare LED-backlit slim, 220 cd/m 2 , 67% sRGB for HD camera and one WLAN antenna (1366 x 768) 8,10

39.6 cm (15.6") diagonal HD SVA eDP anti-glare LED-backlit slim, 220 cd/m 2 , 67% sRGB for HD camera and two WLAN antennas (1366 x 768) 8,10

39.6 cm (15.6") diagonal HD SVA eDP anti-glare LED-backlit slim, 220 cd/m 2 , 67% sRGB for HD+IR camera and two WLAN antennas (1366 x 768) 8,10

39.6 cm (15.6") diagonal HD SVA eDP anti-glare LED-backlit slim, 220 cd/m 2 , 67% sRGB for HD camera, WWAN and two WLAN antennas (1366 x 768) 8,10

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/m², 67% sRGB for two WLAN antennas (1920 x 1080)^{8,10}



Technical Specifications

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/m 2 , 67% sRGB for HD camera and one WLAN antenna (1920 x 1080) 8,10

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/m², 67% sRGB for HD camera and two WLAN antennas (1920 x 1080)^{8,10}

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/m 2 , 67% sRGB for HD+IR camera and two WLAN antennas (1920 x 1080) 8,10

39.6 cm (15.6") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/m 2 , 67% sRGB for HD camera, WWAN and two WLAN antennas (1920 x 1080) 8,10

Touch

39.6 cm (15.6") diagonal HD SVA eDP LED-backlit slim touch screen, 220 cd/m 2 , 67% sRGB for HD camera and two WLAN antennas (1366 x 768) 8,10,11

39.6 cm (15.6") diagonal HD SVA eDP LED-backlit slim touch screen, 220 cd/m 2 , 67% sRGB for HD camera, WWAN and two WLAN antennas (1366 x 768) 8,10,11

HDMI

Supports resolutions up to 4K 30Hz

8. HD content required to view HD images.

10. Resolutions are dependent upon monitor capability, and resolution and color depth settings.

11. Sold separately or as an optional feature.

Docking station model	Total number of supported displays (incl. the notebook display)	Max. resolutions supported	Dock Connectors	Technical limitations
HP Thunderbolt Dock 120W G2	3	Dual 4k @60Hz	2xDP, 1xVGA, 1xTB,1xUSB-C alt- mode	Dual 4k only with one display in to DP and + TB port or USB-C alt mode + TB port
HP USB-C Dock G4	3	Dual 2K @ 60Hz Single 4K @ 60Hz (3840 x 1440)	1xHDMI, 2xDP	
HP USB-C Universal Dock	3	Dual 4K @ 60Hz Single 5K @ 60Hz	2xDP	
HP USB-C Travel Dock	2	Single 2K @ 60Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time
HP USB-C Mini Dock	2	Single 4K @ 30Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time

STORAGE AND DRIVES

Primary Storage

500 GB 7200 rpm SATA¹² 1 TB 5400 rpm SATA¹² 1 TB 7200 rpm SATA (LA Only)¹²



Technical Specifications

Primary M.2 Storage

128 GB M.2 SATA TLC Solid State Drive¹²
256 GB PCIe® NVMe™ M.2 Value Solid State Drive¹²
512 GB PCIe® NVMe™ M.2 TLC Solid State Drive¹²
512 GB PCIe® NVMe™ M.2 Value Solid State Drive¹²
1 TB PCIe® NVMe™ M.2 TLC Solid State Drive¹²

12. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

Note: PCIe SSD not available for Celeron

MEMORY

Maximum Memory

32 GB DDR4-2400 SDRAM13

Memory

32 GB DDR4-2400 SDRAM (2 X 16 GB)¹³
16 GB DDR4- 2400 SDRAM (1 X 16 GB)
16 GB DDR4- 2400 SDRAM (2 X 8 GB)¹³
12 GB DDR4- 2400 SDRAM (4 GB and 8 GB (1 x 8 GB)¹³
8 GB DDR4- 2400 SDRAM (1 x 8 GB)
8 GB DDR4- 2400 SDRAM (2 x 4 GB)¹³
4 GB DDR4- 2400 SDRAM (1 x 4 GB)

Memory Slots

2 SODIMM Both slots are customer accessible / upgradeable DDR4 PC4 SODIMMS, system runs at 2400 Supports Dual Channel Memory

13. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

WLAN

Intel® Dual Band Wireless-AC 9560 802.11ac (2x2) WLAN and Bluetooth® 5.0 Combo, non-vPro™14
Realtek RTL8821CE 802.11ac (1x1) WLAN + Bluetooth®4.2 Combo¹⁴
Realtek RTL8822BE 802.11ac (2x2) WLAN + Bluetooth®4.2 Combo¹⁴

WWAN

Intel® XMM™ 7262 LTE-Advanced (Cat6)¹5 Intel® XMM™ 7360 LTE-Advanced (Cat9)¹5

Ethernet

Realtek RTL8111HSH-CG 10/100/1000 GbE NIC16

14. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications



Technical Specifications

differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

- 15. WWAN module requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.
- 16. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

AUDIO/MULTIMEDIA

Audio

Integrated Microphone (Mono or Dual Array)
2 Integrated Stereo Speakers

Speaker Power

2W/4ohm per Speaker

Camera

720p HD Camera⁸
720p HD Camera+IR Camera^{8,17}

- 8. HD content required to view HD images.
- 17. Sold separately or as an optional feature.

KEYBOARDS/POINTING DEICES/BUTTONS & FUNCTION KEYS

Kevboard

HP Premium Keyboard, spill resistant with optional backlit function

Pointing Device

Clickpad with multi-touch gesture support

Function Keys

- F1 Display Switching
- F2 Blank
- F3 Brightness Down
- F4 Brightness Up
- F5 Audio Mute
- F6 Volume Down
- F7 Volume Up
- F8 Mic Mute
- F9 Blank or Backlit Toggle
- F10 Blank
- F11 Wireless
- F12 Sleep

Hidden Functions

- Fn+R Break
- Fn+S Sys Rq
- Fn+C Scroll Lock



Technical Specifications

SOFTWARE AND SECURITY

BIOS

HP BIOSphere Gen418

HP DriveLock & Automatic DriveLock

BIOS Update via Network

Secure Erase¹⁹

Absolute Persistence Module²⁰

Pre-boot Authentication

HP Wireless Wakeup

Software

HP Native Miracast Support²¹

HP LAN-Wireless Protection

HP Connection Optimizer

HP 3D DriveGuard

HP Hotkey Support - CMIT

HP Jumpstart

HP Support Assistant²²

HP Noise Cancellation Software

HP Host Based MAC Address Manager

Buy Office (sold separately)

Manageability Features

HP Driver Packs²³

HP System Software Manager (SSM)

HP BIOS Config Utility (BCU)

HP Client Catalog

HP Manageability Integration Kit Gen2²⁴

Ivanti Management Suite²⁵

HP Cloud Recovery²⁶

Client Security Software

HP Client Security Suite Gen4²⁷ including:

HP Security Manager²⁸ (including Credential Manager, HP Password Manager, HP Spare Key)

HP Device Access Manager²⁹

HP Power On Authentication

HP Fingerprint Sensor

Windows Defender³⁰



Technical Specifications

Security Management

Secure Erase¹⁹

TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)³¹

SATA 0,1 port disablement (viaBIOS)

RAID configurations³²

Serial, USB enable/disable (viaBIOS)

Power-on password (viaBIOS)

Setup password (viaBIOS)

Support for chassis padlocks and cable lock devices

Integrated hood sensor

HP Sure Click³³

- 18. HP BIOSphere Gen4 requires Intel(R) or AMD 8th Gen processors. Features may vary depending on the platform and configurations.
- 19. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method.
- 20. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
- 21. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming
- 22. HP Support Assistant requires Windows and Internet access.
- 23. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 24. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html.
- 25. Ivanti Management Suite subscription required.
- 26. HP Cloud Recovery is available for HP Elite and Pro desktops and laptops PCs with Intel® or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630
- 27. HP Client Security Suite Gen 4 requires Windows and Intel® or AMD 8th generation processors.
- 28. HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.
- 29. HP Device Access Manager requires HP Client Security Suite Gen4.
- 30. Windows Defender Opt in and internet connection required for updates.
- 31. Firmware TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).
- 32. RAID configuration is optional and does require a second hard drive.
- 33. HP Sure Click is available on most HP PCs and supports Microsoft® Internet Explorer and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode when Microsoft Office or Adobe Acrobat are installed.



Technical Specifications

POWER

Power Supply

HP Smart 65 W External AC power adapter³⁴
HP Smart 65 W EM External AC power adapter³⁴
HP Smart 65 W USB Type-C[™] adapter³⁴
HP Smart 45 W External AC power adapter³⁴
HP Smart 45 W USB Type-C[™] adapter³⁵

Primary Battery

3-cell, 45 Wh Long Life Li-ion35

Battery Life

Up to 12 hours and 30 minutes³⁶

Power Cord

3-wire plug - 1m³⁴
3-wire plug - 1.8m³⁴
2-wire plug - 1m³⁴
Duckhead power cord- 1.0m³⁴
Duckhead power cord- 1.8m³⁴

Battery Weight

0.49 lb 0.22 kg

- 34. Availability may vary by country.
- 35. Battery is internal and not replaceable by customer. Serviceable by warranty.
- 36. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Weight

Starting at 4.41 lbs³⁷ Starting at 2.0 kgs³⁷

Dimensions (w x d x h)

14.37 x 10.11 x 0.75 in 36.49 x 25.69 x 1.9 cm

37. Weight will vary by configuration.

PORTS/SLOTS

Ports

1 USB 3.1 Type-C[™] Gen 1 (Power delivery, DisplayPort[™] 1.2) 1 USB 2.0 (Powered port) 2 USB 3.1



Technical Specifications

1 HDMI 1.4b³⁸

1 RJ-45

1 AC power

1 Headphone/microphone combo jack

Expansion Slots

1 SD

Supports SD, SDHC, SDXC

38. HDMI cable sold separately.

SERVICE AND SUPPORT

HP Services offers 3-year and 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life Batteries which will have same 1-year or 3-year limited warranty as the platform. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc. 39

39. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

ENVIRONMENTAL & INDUSTRY

HP Probook 450 G6 Notebook PC

OK PC				
This product has received or is in the process of being certified to the following approvals and may				
be labeled with one or more of thes	be labeled with one or more of these marks:			
•IT ECO declaration				
•US ENERGY STAR®				
•EPEAT® Silver registered in the United States. See http://www.epeat.net for registration status in				
ystem Configuration The configuration used for the Energy Consumption and Declared Noise Emissions data Notebook model is based on a Typically Configured Notebook.				
115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz		
5.97 W	5.86 W	5.96 W		
2.96 W	3.14 W	3.00 W		
0.79 W	0.81 W	0.79 W		
0.39 W	0.42 W	0.39 W		
Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model				
family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S.				
Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model				
family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is				
	•			
	This product has received or is in the be labeled with one or more of thes IT ECO declaration US ENERGY STAR® EPEAT® Silver registered in the Unityour country. TCO or TCO Certified Edge The configuration used for the Ener Notebook model is based on a Typic 115VAC, 60Hz 5.97 W 2.96 W 0.79 W 0.39 W Energy efficiency data listed is for a family. HP computers marked with the Environmental Protection Agency (Efamily does not offer ENERGY STAR)	This product has received or is in the process of being certified to the be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR® EPEAT® Silver registered in the United States. See http://www.epeayour country. TCO or TCO Certified Edge The configuration used for the Energy Consumption and Declared Not Notebook model is based on a Typically Configured Notebook. 115VAC, 60Hz 5.97 W 5.86 W 2.96 W 3.14 W 0.79 W 0.81 W 0.39 W Energy efficiency data listed is for an ENERGY STAR® compliant prod family. HP computers marked with the ENERGY STAR® specification Environmental Protection Agency (EPA) ENERGY STAR® specification		



Microsoft Windows® operating system.

Technical Specifications

Heat Dissipation*	115	VAC, 60Hz	230VAC	, 50Hz	100VAC, 60Hz	
Normal Operation (Short idle)	20) BTU/hr	20 BT	J/hr	18 BTU/hr	
Normal Operation (Long idle)	10) BTU/hr	11 BTU/hr		10 BTU/hr	
Sleep	3	BTU/hr	3 RTI	I/hr	3 BTU/hr	
Off		BTU/hr	3 BTU/hr 1 BTU/hr		1 BTU/hr	
	Heat dissipation is calculated based on the measured watts, assuming the service level for one hour.				the service level is attained	
Declared Noise	Sound Power Sound Pressure			ound Pressure		
Emissions		(L _{WAd} , bels)		(I	(L _{pAm} , decibels)	
(in accordance with ISO 7779 and ISO 9296)						
Typically Configured — Idle		3			26.6	
Fixed Disk – Random writes		3			26.7	
	 3 USB ports 1 PC card slot (type I/II) 1 ExpressCard/54 slot 1 IEEE 1394 Port 2 SODIMM memory slots Optional expansion base docking station 1 multi-bay II storage port Interchangeable HDD Spare parts are available throughout the warranty period and or for up to "5" years after the end of					
Batteries	production. This battery(s) in this product comply with EU Directive 2006/66/EC					
	Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight					
	Battery size: CR2032 (coin cell)					
Additional Information	Battery type: lithium/manganese dioxide This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.					
 This HP product is designed to comply with the Waste Electrical and Electronic Equip Directive – 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Water and Toxic Enforcement Act of 1986). 			• •			
	 This product is in compliance with the IEEE 1680.1 (EPEAT) standard at the Silver level, see http://www.epeat.net Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO This product contains 12.7% post-consumer recycled plastic (by wt.) This product is 96.2% recycle-able when properly disposed of at end of life. 			d per ISO11469 and ISO1043.		
Packaging Materials	External:	PAPER/Corrugated		295 g		
	Internal:	PLASTIC/Polyethy	lene Expanded - EP	<u> </u>	68 g	
		, ,	•		10 q	
Material Usage	PLASTIC/Polyethylene low density – LDPE 10 g This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):					



Technical Specifications

	• Asbestos
	Certain Azo Colorants
	Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
	• Cadmium
	Chlorinated Hydrocarbons
	Chlorinated Paraffins
	• Formaldehyde
	Halogenated Diphenyl Methanes
	• Lead carbonates and sulfates
	• Lead and Lead compounds
	Mercuric Oxide Batteries
	Nickel – finishes must not be used on the external surface designed to be frequently handled or
	carried by the user.
	Ozone Depleting Substances
	Polybrominated Biphenyls (PBBs)
	Polybrominated Biphenyl Ethers (PBBEs)
	Polybrominated Biphenyl Oxides (PBBOs)
	Polychlorinated Biphenyl (PCB)
	Polychlorinated Terphenyls (PCT)
	• Polyvinyl Chloride (PVC) — except for wires and cables, and certain retail packaging has been
	voluntarily removed from most applications.
	Radioactive Substances
	Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	• Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging
	materials.
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	Design packaging materials for ease of disassembly.
	Maximize the use of post-consumer recycled content materials in packaging materials.
	• Use readily recyclable packaging materials such as paper and corrugated materials.
	Reduce size and weight of packages to improve transportation fuel efficiency.
	Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To
and Recycling	recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest
and Recycling	HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible
	manner.
	manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for
	each product type for use by treatment facilities. This information (product disassembly
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers.
	These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM
	customers who integrate and re-sell HP equipment.
HP Inc. Corporate	For more information about HP's commitment to the environment:
Environmental	To more information about the 3 commitment to the environment.
Information	Global Citizenship Report
Intornacion	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K
	_Certificate.pdf
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf



Technical Specifications

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)

Nominal Operating Voltage 19V
Average Operating Power Win 10
Integrated graphics 5.71W
Discrete Graphics 6.78W

Max Operating Power Discrete < 65W

UMA < 45W

Temperature

Operating 32° to 95° F (0° to 35° C) Non-operating -4° to 140° F (-20° to 60° C)

Relative Humidity

Operating 10% to 90%, non-condensing

Non-operating 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Shock

Operating 40 G, 2 ms, half-sine Non-operating 200 G, 2 ms, half-sine

Random Vibration

Operating 0.75 grms
Non-operating 1.50 grms

Altitude (unpressurized)

Operating -50 to 10,000 ft (-15.24 to 3,048 m)

Non-operating -50 to 40,000 ft (-15.24 to 12,192 m)

Yes

Planned Industry Standard

Certifications

UL Yes
CSA Yes
FCC Compliance Yes

Energy Star® Selected models ⁴⁰ EPEAT® 2019 Yes, Silver in U.S. ⁴¹

ICES Yes Australia Yes **NZ A-Tick Compliance** Yes CCC Yes Japan VCCI Compliance Yes KC Yes **BSMI** Yes **CE Marking Compliance** Yes **BNCI or BELUS** Yes CIT Yes GOST Yes

Saudi Arabian Compliance (ICCP)



Technical Specifications

SABS Yes UKRSERTCOMPUTER Yes

- 40. Configurations of the HP ProBook 450 G6 that are ENERGY STAR® certified are identified as HP ProBook 450 G6 ENERGY STAR on HP websites and on http://www.energystar.gov.
- 41. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit http://www.epeat.net for more information.

DISPLAYS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Panel LCD 14 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 45% NTSC 250 nits eDP slim

 Outline Dimensions (W x H x D)
 316.17 x 197.98 (max)

 Active Area
 309.37 x 174.02 (typ.)

Weight 285 g (max)

Diagonal Size 14.0 inch

Thickness 3.0 mm (max)

Interface eDP 1.2 (2 lane)

Surface Treatment Anti-glare

Touch Enabled No

Contrast Ratio600:1 (typ)Refresh Rate60 HzBrightness250 nits

Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB Backlight LED

Color Gamut Coverage 45% of NTSC

Color Depth 6 bits

Viewing Angle UWVA 85/85/85

Panel LCD 15.6 inch diagonal FHD (1920 x 1080) Anti-Glare WLED UWVA 45% cg 220nits eDP slim NB nontouch

 Outline Dimensions (W x H x D)
 350.96 x 216.75 (max.)

 Active Area
 344.16 x 193.59 (typ.)

Weight <370 g max.
Diagonal Size 15.6"

Thickness 3.2 mm max.
Interface eDP 1.2
Surface Treatment Anti-glare

Touch Enabled No



Technical Specifications

Contrast Ratio 600:1 (typ) - AG

Refresh Rate 60 Hz

Brightness 220 nits typical (Panel Only)

Pixel Resolution 1920 x 1080 (FHD)

Format RGB
Backlight LED
Color Gamut Coverage 45%

Color Depth 6 bits + Hi FRC **Viewing Angle** UWVA 85/85/85/85

Panel LCD 15.6 inch diagonal HD (1366 x 768) Anti-Glare WLED SVA 45% cg 220nits eDP 1.2 w/o PSR slim NB non-touch

 Outline Dimensions (W x H x D)
 350.96 x 216.75 (max.)

 Active Area
 344.16 x 193.59 (typ.)

Weight <370 g max.

Diagonal Size 15.6"

Thickness 3.2 mm max.
Interface eDP 1.2
Surface Treatment Anti-glare

Touch Enabled No

Contrast Ratio300:1 (typ)Refresh Rate60 Hz

Brightness 220 nits typical (Panel Only)

Pixel Resolution 1366 x 768 (HD)

Format RGB
Backlight LED
Color Gamut Coverage 45%

Color Depth 6 bits + Hi FRC **Viewing Angle** SVA 40/40/15/30

Panel LCD 15.6 inch diagonal HD (1366 x 768) WLED SVA 45% cg 220nits eDP 1.2 w/o PSR slim NB touch

 Outline Dimensions (W x H x D)
 350.96 x 216.75 (max.)

 Active Area
 344.16 x 193.59 (typ.)

Weight <568 g max.

Diagonal Size 15.6"

Thickness 3.4 mm max.
Interface eDP 1.2

Surface Treatment BrightView Glass

Touch Enabled Yes

Contrast Ratio 300:1 (typ)
Refresh Rate 60 Hz

Brightness 220 nits typical (Panel Only)

Pixel Resolution 1366 x 768 (HD)



Technical Specifications

Format RGB
Backlight LED
Color Gamut Coverage 45%

Color Depth 6 bits + Hi FRC **Viewing Angle** SVA 40/40/15/30

STORAGE AND DRIVES

Hard Drives

500 GB 7200 rpm SATA Hard Drive Drive Weight0.20 lbs (92 g) ~ 0.21 lbs (95 g)Rotation speed7200 rpmCache BufferUp to 32 MBUnit of the control of the co

 Height
 0.28 in (7 mm)

 Width
 2.75 in (69.85 mm)

 Interface
 ATA-8, SATA 3.0

Transfer Rate 600 MB/s

Seek Time Single Track: 2 ~ 1.5 ms;

Average: 11 ~ 13 ms; Maximum: 18 ~ 22 ms

Logical Blocks 976,773,168

Operating Temperature 32° to 140° F (0° to 60° C) [top cover temp]

Security Features ATA Security

Features S.M.A.R.T., NCQ, Ultra DMA

1 TB 5400 rpm SATA Hard Drive

Rotation speed Cache Buffer Height Width Interface

Drive Weight

Transfer Rate

0.21 lbs (94 g)
5400 rpm
Up to 32 MB
0.28 in (7.2 mm)
2.75 in (69.85 mm)
ATA-8, SATA 3.0
600 MB/s

Seek Time Single Track2 ms Average12 ~ 13 ms

Maximum18 ~ 22 ms

Logical Blocks 1,953,525,168

Operating Temperature 32° to 140° F (0° to 60° C) [top cover temp]

Security Features ATA Security

Features S.M.A.R.T., NCQ, Ultra DMA

SSD 128 GB 2280 M2 SATA- Form Factor
3 TLC Capacity

Capacity NAND Type M.2 2280 128GB TLC



Technical Specifications

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Weight 0.02 lb (10 g)
Interface ATA-8, SATA 3.0
Maximum Sequential Read Up To 520 MB/s
Maximum Sequential Write Up To 450 MB/s
Logical Blocks 250,069,680

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features DIPM; TRIM; DEVSLP

256 GB 2280 PCIe NVMe Value Solid State Drive Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3Maximum Sequential ReadUp To 1700 MB/sMaximum Sequential WriteUp To 1300 MB/sLogical Blocks500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

512 GB 2280 M2 PCIe NVMe Form Factor **TLC Solid State Drive** Capacity

Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Interface PCIe NVMe Gen3X4
Maximum Sequential Read Up To 2600 MB/s
Maximum Sequential Write Up To 1400 MB/s
Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

16 GB 2280 PCIe-3x2 NVMe Form Factor 3D Xpoint Solid State Drive Canacity

Form Factor M.2 2280
Capacity 16 GB
NAND Type Xpoint

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Interface
 PCIe NVMe Gen3X2



Technical Specifications

Maximum Sequential Read1400Maximum Sequential Write300

Logical Blocks 28,181,188

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features L1.2

512 GB 2280 PCIe NVMe Value Solid State Drive Form Factor M.2 2280
Capacity 512 GB
NAND Type Value

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Interface
 0.02 lb (10 g)

Maximum Sequential ReadUp To 1500 ~ 1700 MB/sMaximum Sequential WriteUp To 860 ~ 1500MB/s

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security, TRIM; L1.2



Technical Specifications

NETWORKING/COMMUNICATIONS

Intel® XMM™ 7360 LTE- Technology/Operating Advanced CAT91

bands

FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower). 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850

(Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66).

TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41).

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MHz

Wireless protocol standards

3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to

450Mbps: UL 20MHz throughput up to 50Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz

Maximum data rates LTE: 450 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)

Maximum output power

LTE: 23 dBm HSPA+: 23.5 dBm

Maximum power consumption

LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 5.8 q

Dimensions 42 x 30 x 2.3 mm

(Length x Width x Thickness)

> WWAN module is optional, must be configured at the factory and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

Intel® XMM™ 7262 LTE-Advanced DL CAT6¹

Technology/Operating bands

FDD LTE: 2100 (Band 1), 1800 (Band 3), 850 (Band 5), 2600 (Band 7), 900

(Band 8), 800 (Band 20), 700 (Band 28),

HSPA+: 2100 (Band 1), 850 (Band 5), 900 (Band 8)

Wireless protocol standards

3GPP Release 11 LTE Specification CAT.6. DL 40MHz BW throughput up to

300Mbps; UL 20MHz throughput up to 50Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B and XTRA)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz

Maximum data rates LTE: 300 Mbps (Download), 50 Mbps (Upload)

> DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)

LTE: 23 dBm Maximum output power

HSPA+: 23.5 dBm

LTE: 1,200 mA (peak); 830 mA (average) **Maximum power** consumption HSPA+: 1,100 mA (peak); 680 mA (average)



Technical Specifications

Form Factor M.2, 3042-S3 Key B

Weight 6 g

Dimensions 42 x 30 x 2.3 mm

(Length x Width x Thickness)

> 1. WWAN module is optional, must be configured at the factory and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

WLAN

Intel® 9560 802.11a/b/g/n/ac (2x2) WLAN and Bluetooth® 5.0 Combo¹ non-vPro

Wireless LAN Standards

IEEE 802.11a IEEE 802.11b IEEE 802.11q IEEE 802.11n IEEE 802.11ac IEEE 802.11d IEEE 802.11e IEEE 802.11h IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v Wi-Fi® certified

Interoperability **Frequency Band**

802.11b/g/n • 2.402 - 2.482 GHz

802.11a/n/ac

 4.9 – 4.95 GHz (Japan) • 5.15 - 5.25 GHz • 5.25 - 5.35 GHz • 5.47 - 5.725 GHz • 5.825 - 5.850 GHz

Data Rates

• 802.11b: 1, 2, 5.5, 11 Mbps

• 802.11q: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, , 80MHz &

160MHz)

Modulation

Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security³

- IEEE and WiFi® compliant 64 / 128 bit WEP encryption for a/b/g mode only
- AES-CCMP: 128 bit in hardware
- 802.1x authentication
- WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
- WPA2 certification
- IEEE 802.11i
- Cisco Certified Extensions, all versions through CCX4 and CCX Lite
- WAPI



Technical Specifications

Network Architecture Ad-hoc (Peer to Peer)

Models Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

Output Power² • 802.11b: +18.5dBm minimum

802.11g: +17.5dBm minimum802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +11.5dBm minimum

Power Consumption Transmit mode: 2.0 W

Receive mode: 1.6 W

Idle mode (PSP)180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connected Standby/Modern Standby: 10mW

Radio disabled: 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

Dimensions 1. Type 2230: 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230: 2.8g

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (–10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber – Radio OFF; LED White – Radio ON

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/q (OFDM modulation).



Technical Specifications

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth® Specification 4.0/4.1/4.2/5.0 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy: 0~79 (1 MHz/CH) Channels BLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps signaling data rate1

> BLE: 1 Mbps signaling data rate1 1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 4 dBm for BR and EDR.

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Bluetooth Software

Supported **Link Topology** Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management

Certifications

ETS 300 328. ETS 300 826 Low Voltage Directive IEC950UL, CSA, and CE Mark

BT4.1-ESR 5/6/7 Compliance

Bluetooth Profiles

Supported

LE Link Layer Ping

LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Realtek 802.11a/b/g/n/ac (2x2) WLAN and Bluetooth® 4.2 Combo¹

Wireless LAN Standards IEEE 802.11a IEEE 802.11b IEEE 802.11g

IEEE 802.11n IEEE 802.11ac

Wi-Fi® certified Interoperability



Technical Specifications

Frequency Band 802.11b/g/n

2.402 – 2.482 GHz

802.11a/n/ac

• 4.9 – 4.95 GHz (Japan)

• 5.15 - 5.25 GHz • 5.25 - 5.35 GHz • 5.47 - 5.725 GHz

5.825 – 5.850 GHz

Data Rates • 802.11b: 1, 2, 5.5, 11 Mbps

> • 802.11q: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz)

Modulation **Direct Sequence Spread Spectrum**

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security³

IEEE and WiFi® compliant 64 / 128 bit WEP encryption for a/b/g mode only

AES-CCMP: 128 bit in hardware

802.1x authentication

WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification

IEEE 802.11i

Cisco Certified Extensions, all versions through CCX4 and CCX Lite

WAPI

Network Architecture

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Roaming Output Power² IEEE 802.11 compliant roaming between access points

 802.11b: +14dBm minimum • 802.11g: +12dBm minimum

• 802.11a: +12dBm minimum

 802.11n HT20(2.4GHz): +12dBm minimum • 802.11n HT40(2.4GHz): +12dBm minimum 802.11n HT20(5GHz): +10dBm minimum • 802.11n HT40(5GHz): +10dBm minimum

802.11ac VHT80(5GHz): +10dBm minimum

Power Consumption Transmit mode 2.0 W

Receive mode 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated)

Connected Standby 10 mW Radio disabled 8 mW

ACPI and PCI Express compliant power management **Power Management**

802.11 compliant power saving mode

Receiver Sensitivity³ 802.11b, 1Mbps: -93.5dBm maximum

> 802.11b, 11Mbps: -84dBm maximum 802.11a/q, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum

802.11n, MCS15: -64dBm maximum



Technical Specifications

802.11ac, MCS0: -84dBm maximum 802.11ac. MCS9: -59dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

Dimensions Type 2230: 2.3 x 22.0 x 30.0 mm

 Weight
 Type 2230: 2.8g

 Operating Voltage
 3.3v +/- 9%

Temperature Operating 14° to 158° F (–10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

LED Amber – Radio OFF; LED White – Radio ON

1. Check latest software/driver release for updates on supported security features.

2. Maximum output power may vary by country according to local regulations.

3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.2 Wireless Technology

Bluetooth Specification 4.0/4.2 Compliant
Frequency Band 2402 to 2480 MHz
Number of Available Legacy: 0~79 (1 MHz/CH)

Channels BLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps signaling data rate¹

BLE: 1 Mbps signaling data rate¹
1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 4 dBm for BR and EDR.

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Electrical Interface USB 2.0 compliant

Bluetooth Software

Software Microsoft Windows Bluetooth Software

Supported Link Topology Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support **Certifications** FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management ETS 300 328, ETS 300 826

Certifications Low Voltage Directive IEC950UL, CSA, and CE Mark



Technical Specifications

Bluetooth Profiles
Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping

LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Laver Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Realtek

802.11a/b/g/n/ac (1x1) WLAN and Bluetooth® 4.2 Combo¹ **Wireless LAN Standards**

IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac

Interoperability Frequency Band Wi-Fi certified 802.11b/g/n

• 2.402 - 2.482 GHz

802.11a/n

4.9 – 4.95 GHz (Japan)
5.15 – 5.25 GHz
5.25 – 5.35 GHz
5.47 – 5.725 GHz
5.825 – 5.850 GHz

Data Rates

• 802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)

Modulation

Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security³

 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only

AES-CCMP: 128 bit in hardware

• 802.1x authentication

WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification

IEEE 802.11i

Cisco Certified Extensions, all versions through CCX4 and CCX Lite

WAPI

Network Architecture Models Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Not all configuration components are available in all regions/countries. c06142921 — DA 16312 - Worldwide — Version 15 — October 11, 2019



Technical Specifications

Roaming IEEE 802.11 compliant roaming between access points

Output Power² • 802.11b: +14dBm minimum

• 802.11g: +12dBm minimum • 802.11a: +12dBm minimum

802.11n HT20(2.4GHz): +12dBm minimum
802.11n HT40(2.4GHz): +12dBm minimum
802.11n HT20(5GHz): +10dBm minimum
802.11n HT40(5GHz): +10dBm minimum
802.11ac VHT80(5GHz): +10dBm minimum

Power Consumption Transmit mode 2.0 W

Receive mode 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated) Idle mode 50 mW (WLAN unassociated)

Connected Standby 10 mW Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

Dimensions Type 2230: 2.3 x 22.0 x 30.0 mm

 Weight
 Type 2230: 2.8g

 Operating Voltage
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Temperature Operating 14° to 158° F (–10° to 70° C)

Non-operating –40° to 176° F (–40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber – Radio OFF; LED White – Radio ON

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology

Bluetooth Specification4.0/4.1/4.2 CompliantFrequency Band2402 to 2480 MHzNumber of AvailableLegacy: 0~79 (1 MHz/CH)



Technical Specifications

Channels BLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps signaling data rate¹

BLE: 1 Mbps signaling data rate¹
1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 4 dBm for BR and EDR.

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Electrical Interface

Bluetooth Software

Supported

Link Topology

Power Management

Certifications

Power Management Certifications

Bluetooth Profiles

Supported

USB 2.0 compliant

Microsoft Windows Bluetooth Software

Microsoft Windows ACPI, and USB Bus Support FCC (47 CFR) Part 15C, Section 15.247 & 15.249

ETS 300 328. ETS 300 826

Low Voltage Directive IEC950UL, CSA, and CE Mark

BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping

LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising
LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 —Link Layer Privacy

LE Privacy 1.2 -Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

POWER

HP 45W Smart AC adapter Dimensions (H x W x D) 3.74 x 1.57 x 1.04 in (9.5 x 4.0 x 2.65 cm)

 Weight
 0.386 lb (175g) max

 Input
 90 to 265 VAC

Input Efficiency 87.74% at 115Vac and 88.4% at 230Vac

Input frequency range 47 to 63 Hz



-4° F to 185° F (-20° to 85° C)

QuickSpecs

Technical Specifications

Input AC current 1.4 A at 90 VAC

Output Output power 45W

DC output 19.5V

Hold-up time 5 msec at 115 VAC input

Output current limit <8.0A

Connector 4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords

Environmental Design Operating 32° F to 95° F (0° to 35° C)

temperature

Non-operating (storage)

temperature

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity20% to 95%Storage Humidity10% to 95%

EMI and Safety Certifications *CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

HP 65W Smart AC adapter Dimensions 90x51x28.5mm

Weight unit: 220g +/- 10g

Input Input Efficiency 88% min at 115 VAC and 89% min at 230 VAC

Input frequency range 47 to 63 Hz

Input AC current 1.7 A at 90 VAC

Output Output power 65W

DC output 19.5V

Hold-up time 5 msec at 115 VAC input

Output current limit <11.0A

Connector 4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords

Environmental Design Operating 32°F to 95°F (0°to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature

Altitude 0 to 16.400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications *CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.



Technical Specifications

* MTBF - over 200.000 hours at 25°C ambient condition.

HP 65W EM Smart AC adapter

Dimensions 102x55x30mm Weight 270g +/- 10g

Input **Input Efficiency** 87% min at 115V/230V

> Input frequency range 47 to 63 Hz

> > **Input AC current** 1.7 A at 90 VAC and maximum load

DC output 65W(19.5V/3.33A) Hold-up time 5 msec at 115 VAC input

<11A, Over voltage protection- 29V max **Output current limit**

automatic shutdown

4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords Operating 0° to 35° C **Environmental Design**

temperature

Non-operating (storage) -20° to 85° C

temperature

Altitude 0 to 5,000 m **Humidity** 0% to 95% **Storage Humidity** 0% to 95%

EMI and Safety Certifications

Connector

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV: Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B.

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 65 Watt nPFC Dimensions **USB** type C

Weight

74x74x28.5mm unit: 245q +/- 10q

Input

Input Efficiency 81.5% min at 115 Vac/ 230Vac @ 5V/3A

> 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

47 to 63 Hz

Input AC current 1.7 A at 90 VAC and maximum load

Output power 65W

Input frequency range

DC output 5V/9V/10V/12V/15V/20V Hold-up time 5ms at 115 Vac input

Output current limit <8.0A

Connector Type C

Environmental Design Operating 0° to 35° C

temperature



Technical Specifications

Non-operating (storage) -20° to 85° C

temperature

Altitude 0 to 5,000 m **Humidity** 0% to 95% **Storage Humidity** 0% to 95%

EMI and Safety Certifications

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

AC Adapter 45 Watt nPFC Dimensions **USB** type C

Weight

Input

62.0x62.0x28.5mm

unit: 220g +/- 10g

Input Efficiency Average Efficiency of 25%, 50%, 75%, 100%

load condition with 115Vac/230Vac Spec:5V: 81.5%9V: 86.7%10V: 87.5%12V: 87.8%15V:

87.8%20V: 87.8%

Input frequency range 47 to 63 Hz

Input AC current Max. 1.4 A at 90 Vac

Output power 5V/15W

9V/27W 10V/37.5W 12V/45W 15V/45W 20V/45W

DC output 5V/9V/10V/12V/15V/20V Hold-up time 5ms at 115 Vac input

Output current limit <5.0A

Connector Type C

Environmental Design Operating 32°F to 95°F (0°to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1. SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200.000 hours at 25°C ambient condition.



Technical Specifications

3 Cell WHr 45 Long Life -Polymer HP Fast Charge Technology¹ **Dimensions (H x W x L)** 6.0. x184.7x88.9 mm

Weight 0.22 kg (0.48lb)
Cells/Type 3cell Lithium-Ion

Voltage 11.55V Amp-hour capacity 3.900Ah Watt-hour capacity 45Wh

Operating (Charging) 32° to 113° F (0° to 45° C)
Operating (Discharging) 14° to 122° F (-10° to 60° C)

1. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode when used with the power adapter provided with the notebook. After charging has reached 50% capacity, charging speed will return to normal. Charging time may vary +/-10% due to System tolerance.



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part Number
Cases	HP Essential Top Load Case	H2W17AA
	HP Essential Backpack	H1D24AA
	HP Essential Messenger Case	H1D25AA
Dockings	HP USB-C Mini Dock	1PM64AA
	HP USB-C Universal Dock	1MK33AA
	HP USB-C Dock G4	3FF69AA
Input/Output	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP HDMI to DVI Adapter	F5A28AA
Memory	4GB 2666MHz DDR4	4VN05AA
	8GB 2666MHz DDR4	4VN06AA
	16GB 2666 MHz DDR4	4VN07AA
Power	HP 45W Smart AC Adapter 4.5mm	H6Y88AA
	HP 65W Slim AC Adapter	H6Y82AA
	HP 65W USB-C Power Adapter	3PN48AA
	HP 45W USB-C Power Adapter	1HE17AA
	HP 65W USB-C Power Adapter	1HE08AA
	HP Power Bank	N9F71AA
	HP USB-C Power Bank	2NA10AA
	HP 45W LC USB-C Power Adapter	1MZ01AA#ABA
Storage	HP External USB Optical Drive	F2B56AA
	HP 500GB 7200rpm HDD	F3B97AA
Security	HP Combination Lock	TOY15AA
	HP Essential Keyed Cable lock 12.3mm	TOY14AA
	HP Keyed Cable Lock 10mm	T1A62AA
	HP UltraSlim Keyed Cable Lock	T1A62AA
UCC	HP Conferencing Keyboard	K8P74AA
	HP Speaker Phone	K7V16AA
	HP Wired Headset	K7V17AA
Displays	HP ProDisplay P223 21.5-inch Monitor	X7R61AA
	HP ProDisplay P232 23-inch Monitor	K7X31AA
	HP ProDisplay P240va 23.8-inch Monitor	X3B48AA
	HP EliteDisplay E243 23.8-inch Monitor	1FH47AA
	HP EliteDisplay E243m 23.8-inch Collaboration Monitor	1FH48AA
	HP EliteDisplay E273 27-inch Monitor	1FH50AA



Summary of Changes

Date of change:	Version History:		Description of change:
December 10, 2018	V1 to V2	Removed	Dock UltraSlim
December 12, 2018	V2 to V3	Removed	Phonewise Software
December 17, 2018	V3 to V4	Added	Environmental Section
December 21, 2018	V4 to V5	Added	Skype in at a glance section
March 7, 2019	V5 to v6	Updated	Passed MIL-STD
March 15, 2019	V6 to V7	Added	Processors
March 27, 2019	V7 to V8	Updated	Storage and drives and Graphic section
April 17, 2019	V8 to V9	Updated	MIL-STD
May 7, 2019	V9 to V10	Updated	At a glance section
June 11, 2019	V10 to V11	Added	HP Cloud Recovery
July 22, 2019	V11 to V12	Added	Speaker Power
September 20, 2019	V12 to V13	Updated	1TB 7200 rpm SATA (LA Only), Lock Slot and 250nits Panel
September 24, 2019	V13 to V14	Added	1TB PCle® to Storage and Drives Section
October 11, 2019	V14 to V15	Added	DisplayPort™ 1.2 and i5-8365U Processor

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